

Electronics for the Future

ROHM Introduces
a New MOSFET for Al Servers
with Industry-Leading*
SOA Performance
and Low ON-Resistance

Endorsed by a major global cloud platform provider

July 1, 2025 ROHM Co., Ltd. Marketing Communication Department

*ROHM July 1, 2025 study on existing 8080-size 100V power MOSFETs

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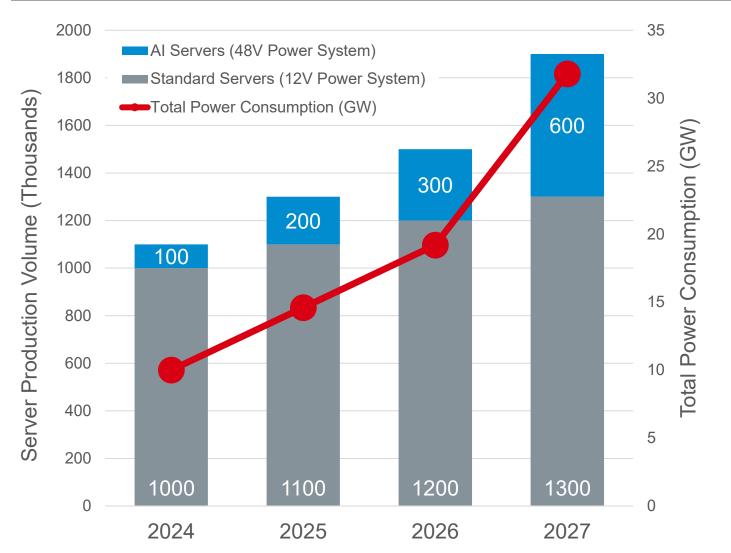
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Power Challenges



Server Production Forecast and Power Consumption Trend



The Al server market is projected to expand by sixfold over the four years starting from 2024



As Al technology rapidly evolves

Power consumption is projected to increase by threefold

Differences Between Al Servers and Conventional Servers



Parameter	Al Servers	Conventional Servers			
Primary Applications	Al inference/training, large-scale data processing, etc.	Web services, file servers, business systems, etc.			
Embedded Processors	GPUs, Al accelerators, etc.	CPU-centered			
Power Supply Configuration	48V systems are mainstream	12V systems are mainstream			
Power Consumption	High (Approx. 3000W or more per unit)	Low (Approx. 600W per unit)			
Cooling Method	Liquid cooling (Air cooling may be insufficient in some cases)	Air cooling is common			
Network Bandwidth	High bandwidth (e.g. high-speed interconnects)	Standard ethernet			

Al servers require higher density, higher load, and higher efficiency power supplies

What is Hot-Swapping in Servers?

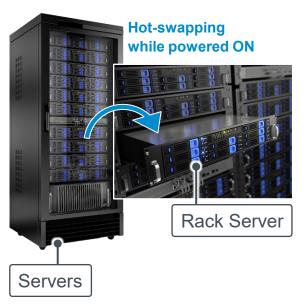


CPU

GPU

FAN

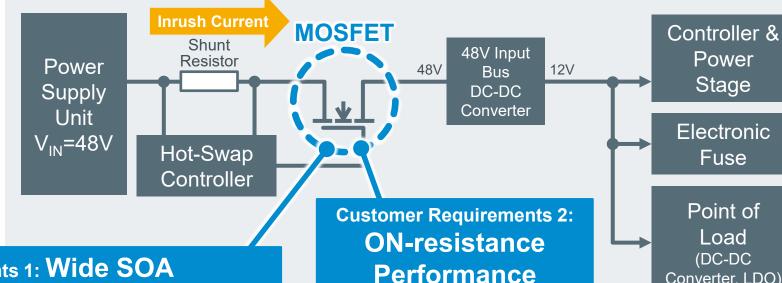
HDD



Sample Schematic Diagram of a Server Power Supply

SOA: Safe Operating Area **HSC:** Hot-Swap Controller

HSC Operation: Prevents inrush current from being instantaneously applied to components



Customer Requirements 1: Wide SOA

HSC Operation Pw=10ms **Inrush Current**

The HSC slowly turns the MOSFET ON

▶ Voltage and current applied with a fixed pulse width

Customer Feedback

Pw=1ms to 10ms required

Energy-saving effect due to

always ON operation

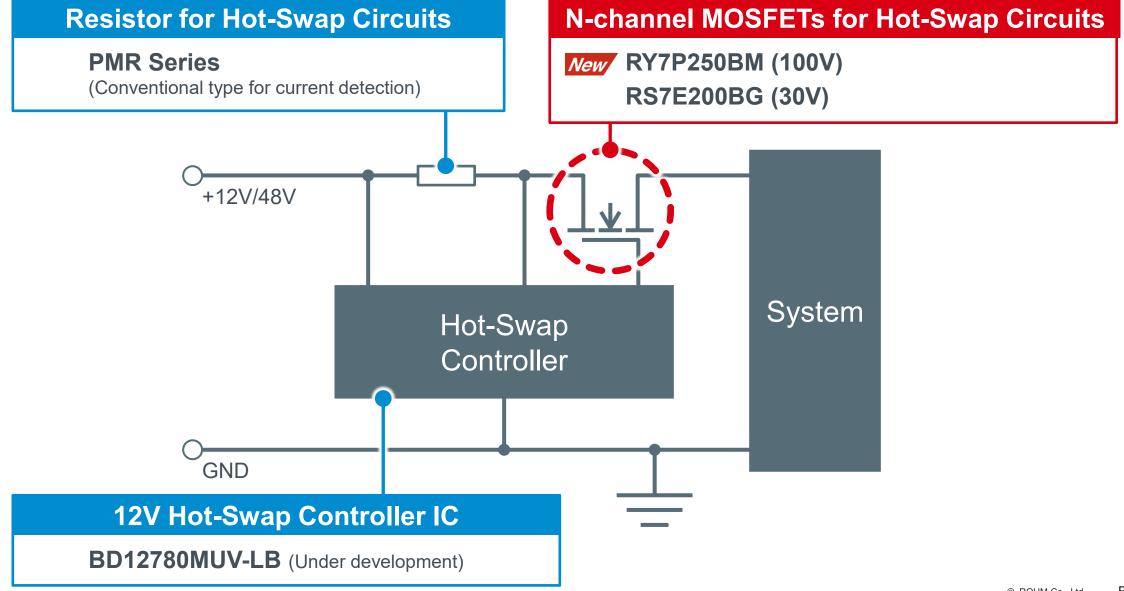
Trend of increasing component power consumption

Large Current = Wide SOA

Converter, LDO)

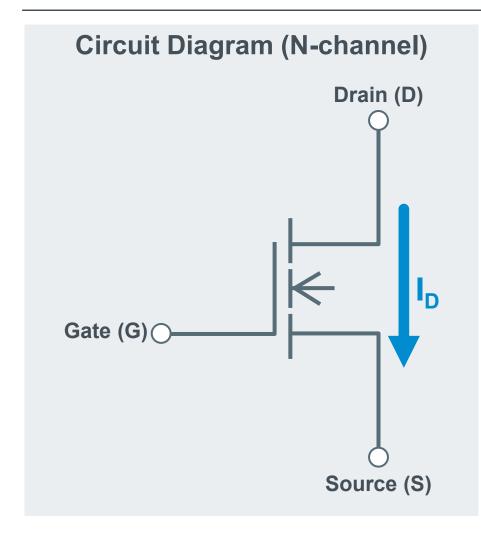
Hot-Swap Circuit





MOSFETs - Key Devices in Power Control





MOSFET Basics

- MOSFET (Metal–Oxide–Semiconductor FET) is an electronic switch for ON/OFF power control
- Used for a wide range of power-related applications such as power conversion, switching, and control circuits

Primary Applications

- Power supply circuits (i.e. buck/boost converters, protection)
- Hot-swap function (safe component replacement while powered ON)
- Motor control circuits (for industrial equipment, home appliances, and power tools)
- Inverter circuits (e.g. solar power systems, electric vehicles)

MOSFETs are essential switching devices for all types of power control

What is EcoMOS™?

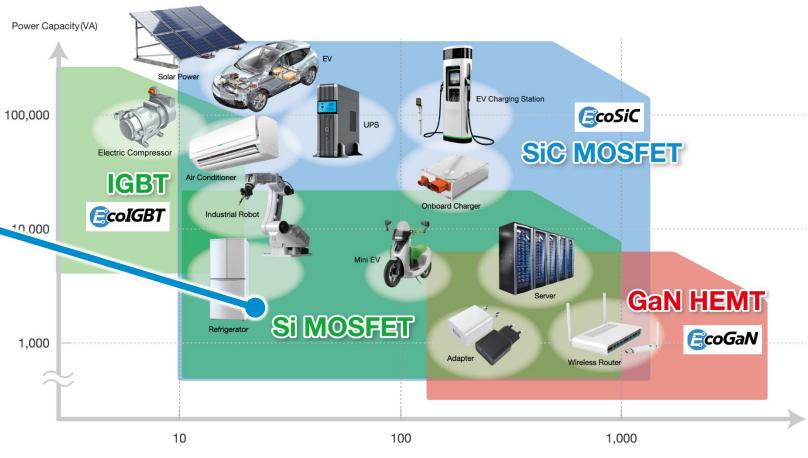


The power capacity and operating frequency range of power devices can vary greatly depending on their materials and structure.

*EcoSiC™ is designed to operate as an SiC MOSFET, while EcoGaN™ is intended to function as a GaN HEMT



EcoMOS™ is ROHM's brand of silicon MOSFETs designed for energy-efficient applications in the power device sector. Widely utilized in applications such as home appliances, industrial equipment, and automotive systems, EcoMOS™ provides a diverse lineup that enables product selection based on key parameters such as noise performance and switching characteristics to meet specific requirements.



EcoMOS™, EcoSiC™, EcoGaN™, and EcoIGBT™ are trademarks or registered trademarks of ROHM Co., Ltd.

Product Overview: RY7P250BM



Features

- 100V power MOSFET ideal for 48V hot-swap circuits
- Industry-leading* SOA and low ON-resistance (R_{DS(on)})
- Standard 8080-size package
- Certified as a recommended component by US cloud provider

RY7P250BM
DFN8080-8S
(8.0mm × 8.0mm × 1.0mm)



*ROHM July 1, 2025 study on existing 8080-size 100V power MOSFETs

Key Specifications

	Part No.	Polarity	V _{DSS} [V]	I _D [A]	$R_{DS(on)}$ Max. [mΩ] V_{GS} =10V	Ciss [pF]	Qg [nC] V _{GS} =10V	SOA V _{GS} Pw=10ms	=48V [A] Pw=1ms	Package [mm]
1	RY7P250BM	N- channel	100	250	1.86	11300	170	16	50	DFN8080-8S (8.0×8.0×1.0)

Product Video

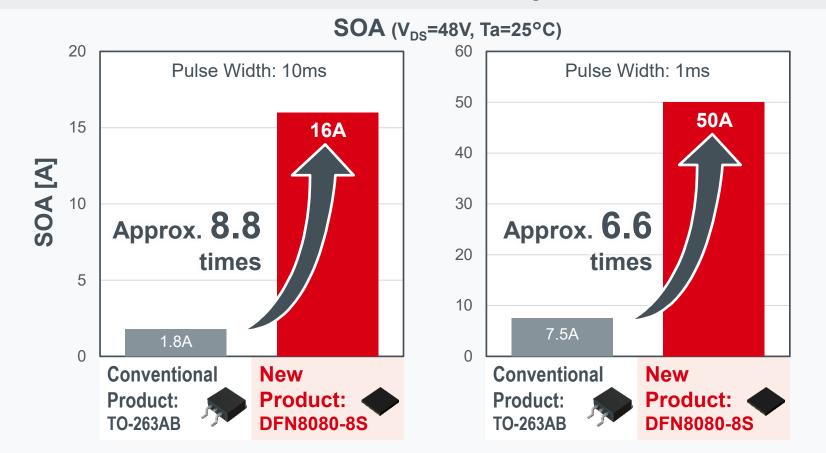




Feature 1: Wide SOA



SOA Performance Comparison

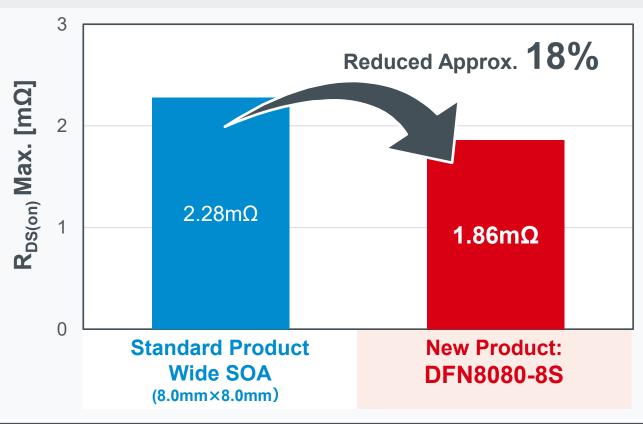


Significantly improved SOA tolerance enhances reliability and durability in high-load environments

Feature 2: Low ON-resistance



ON-resistance Comparison vs Standard 8080-Size Product (V_{GS}=10V, I_D=50A, Tj=25°C)



- Achieves a low ON-resistance of 1.86mΩ
- Deliver higher efficiency, reduced cooling requirements, and lower power costs for server-power supplies

Recommended Product by Cloud Platform Provider



The new product has been certified as a recommended component by leading global cloud platform provider

Key Points Evaluated

Features	Contents				
Wide SOA	Safely handles inrush current and high-current loads during AI processing Meets the reliability standards required for cloud applications				
High-efficiency through low ON-resistance	Reduces cooling load and power consumption by suppressing heat generation Ideal for high-density server operations				
Standard 8080-size package	Easily replaceable in existing circuit designs Mass production system capable of large-scale manufacturing				
Supply system	Stable supply was positively evaluated				

Package Roadmap



High Power Package Compact Package 5060 Size 3333 Size Package indicates JEDEC code. Higher Current **DFN5060 DFN8060** R&D R&D) ROHM package, <> general package code. **Phase** Phase Stack structure 8.0×6.0 **Planned Large Current** Tc=25°C, I_{DSL}) New Announced in May 2025 DFN DFN **DFN8080-8S** Under development 5060FB 5060F △DFN8080T8LSHYAI **TOLL** Double-side Source-down $8.0 \times 8.0 \times 1.0$ cooling (TOLL9LSATAC) $I_D = 300A \text{ to } 635A$ $9.9 \times 10.43 \times 2.3$ (Ta=25°C, **Large Current with Excellent Heat** I_D=195A to 295A **Large Current** Dissipation Announced in February 2025 New Under development Under development **DFN5060-8S** DFN3333FB-9S **DFN3333F-9S** otin(DFN5060T8LSHAAE) (TO-220AB) $3.3 \times 3.3 \times 0.65$ $3.3 \times 3.3 \times 1.0$ $5.0 \times 6.0 \times 1.0$ **DFN2020** (HSML3030L10) $I_D = 50A$ to 210A $I_D = 50A$ to 210A **TO-263AB** Current 10.16×29.07 $I_D = 125A$ to 390A ⊿HUML2020L8 $3.0 \times 3.0 \times 0.6$ Source-down double-Source-down $\times 4.44$ (TO-263AB3LSHYAD) $2.0 \times 2.0 \times 0.6$ $I_D=7A$ to 11A side cooling $I_D = 50A$ to 270A 10.16×15.1×4.57 $I_D=1A$ to 18A $I_D = 40A$ to 260A Drain (TSMT8) (HSMT8) $3.0 \times 2.8 \times 0.8$ (HSOP8) TO-263S TO-252 **TO-220FP** $I_D = 1.5A$ to 11A $3.3 \times 3.3 \times 0.8$ $_{\rm D}$ =6.5A to 125A 5.0×6.0×1.0 <DPAK> <D2PAK> (TO-220FM) (LPTS) 10.0×29.0×4.5 $I_D = 4.5A$ to 300A (TO-252) **DFN1616-7T** SOT-323T. SOT-346T, SOT- $6.6 \times 1.0 \times 2.3$ 10.1×10.0×2.3 I_D =5A to 205A DFN3333-9DC 25T, SOT-457T **SOT-363T** (HEML1616L7) I_D =4A to 150A $I_D=5A$ to 70A(SOP8) (HSML3030L9) 1.6×1.6×0.55 TUMT3, 5, 6 TSMT3, 5, 6 $5.0 \times 6.0 \times 1.75$ $3.3 \times 3.3 \times 0.75$ $I_D = 4.5A$ to 7.5A 2.0×2.1×0.77 $2.9 \times 2.8 \times 0.85$ **Higher Power** I_{D} =5.5A to 7A $I_D = 2.5A$ to 18A $I_{\rm D}$ =0.7A to 6.5A I_{D} =1A to 8.5A



Electronics for the Future

Notes



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